# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





# THIS SPECIFICATION APPLIES TO THE ELECTROMAGNETIC BUZZER

# SPECIFICATION

Test condition: TEMP=+25±2 ℃ Related humidity=65±5% Air pressure:860 ~1060mbar

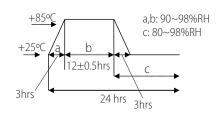
item	unit	specification	condition
rated voltage	Vo-p	3.6	Vo-p
operating volt	Vo-p	2.5 ~ 4.5	
mean current	mA	100 Max	At rated voltage 2730Hz, square wave, 1/2 duty
coil resistance	Ω	16±3	
sound output	dBA	88	At 10cm(A-weight free air), at rated voltage
			2730Hz, square wave, 1/2duty
rated frequency	Hz	2730	
operating temp	°C	-30 ~ +70	
storage temp	°C	-40 ~ +85	
dimension	mm	L8.5×W8.5×H4.0	See attached drawing
weight	gram	0.6	
material		LCP(Black)	
terminal		SMD type	See attached drawing
		(Plating Sn)	
environmental		RoHS	
protection regulation			

#### **ENVIRONMENT TEST**

item	test condition	evaluation standard
 high temp. test	After being placed in a chamber at +85°C for 96 hours.	After the test the part will meet specifications without any degradation in appearance and
 low temp. test	After being placed in a chamber at -40°C for 96 hours.	performance except SPL., after 4 hours at +25°C. The SPL will be in ±10dBA compared with
thermal shock	The part will be subjected to 10 cycles. One cycle shall consist of: -40°C -40°C -40°C -40°C -40°C -40°C -40°C -40°C -40°C -40°C -40°C	initial one.

temp./humidity cycle

The part will be subjected to 10 cycles. One cycle shall be 24 hours and consist of:





# **RELIABILITY TEST**

item	test conditions	evaluation standard
operating life test	ORDINARY TEMPERATURE	After the test the part will meet specifications
	The part will be subjected to 96 hours of	without any degradation in appearance and
	continuous operation at room temperature.	performance except SPL, after 4 hours at +25°C.
	HIGH TEMPERATURE	The SPL would be in ±10dBA compared with
	The part will be subjected to 72 hours of	initial one.
	continuous operation at +70°C with 3.6V,	
	2730Hz applied.	
	LOW TEMPERATURE	-
	The part will be subjected to 72 hours of	
	continuous operation at -30°C with 3.6V, 2730Hz	
	applied.	
TECT CONDITION		

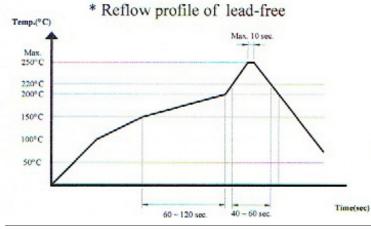
#### TEST CONDITION

Standard Test Condition : a)Temperature: +5~+35°C b)Humidity:45~85% c)Pressure: 860~1060mbar

# **MECHANICAL CHARACTERISTICS**

item	test condition	evaluation standard	
solderability	Lead terminals are immersed in solder bath of $+270\pm5$ °C for $3\pm1$ seconds.	90% min.lead terminals will be wet with solder No interference in operation	
 soldering heat resistance	The product followed the reflow profile to test its reflow thermo-stability.	-	
terminal mechanical strength	Lead pads will be soldered on the pc board, and the force 9.8N(1.0Kg) will be applied behind the part for 10 seconds.	No damage and cutting off	
vibration	The part will be subjected to a vibration cycle of 10Hz to 55Hz to 10Hz in a period of 1 minute. Total peak amplitude will be 1.52mm(9.3G). The vibration test will consist of 2 hours per axis in each three axes (X,Y,Z). Total 6 hours.	After the test the part will meet specifications without any damage in appearance and performance except SPL. SPL would be in $\pm 10$ dBA compared with initial one.	
drop test	The part only will be dropped from a height of 75cm onto a 40mm thick wooden board 3 times in 3 axes (X,Y,Z). Total of 9 times.	-	

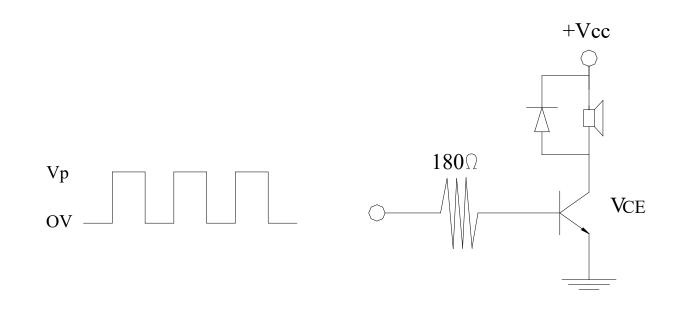
# RECOMMENDED TEMPERATURE PROFILE FOR REFLOW OVEN



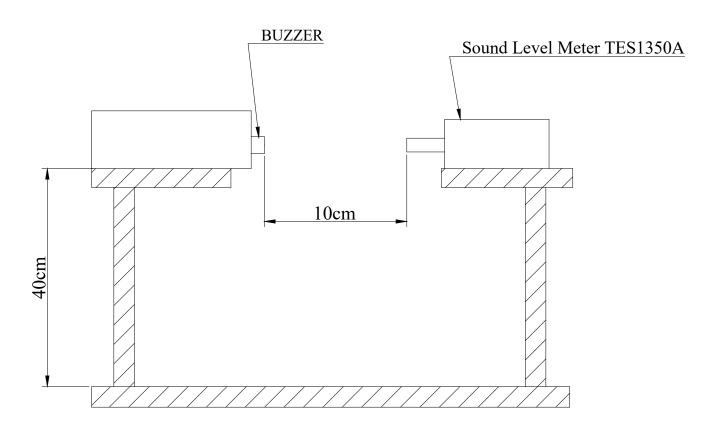
Recommendable wave soldering condition is as follows: Note 1: It is requested that reflow soldering should be executed after heat of product goes down to normal temperature. Note 2: Peak reflow temperature of 250°C maximum of 10 seconds, with a maximum duration of 40-60 seconds between 220°C and 250°C



# MEASUREMENT TEST CIRCUIT



**INSPECTION FIXTURE** 

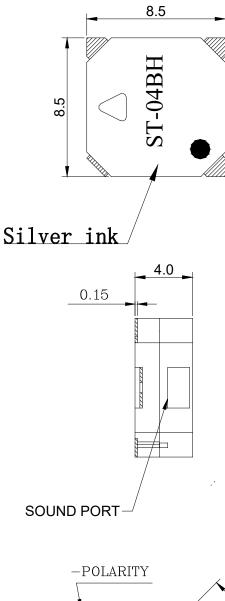


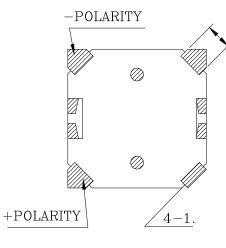


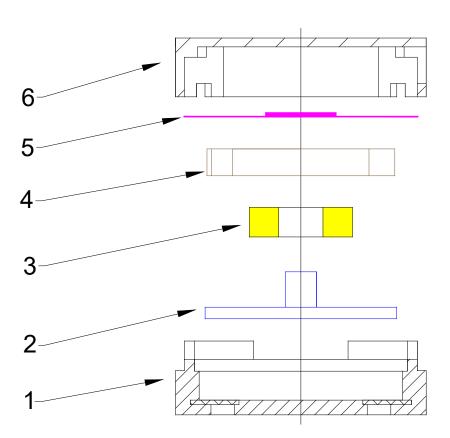
MODEL: ST-04BH PRODUCT: Electromagnetic Buzzer EDITION: A/2016

# DIMENSIONS

Tolerance:±0.5 (unit: mm)







no	item	material	quantity
1	CASE	LCP	1
2	Core	Ferrum	1
3	Coil	Copper	1
4	Magnet ring	NdFeB	1
5	Diaphragm	Ferrum	1
6	CASE	LCP	1



MODEL: ST-04BH PRODUCT: Electromagnetic Buzzer EDITION: A/2016

## PACKING

